

ZXTCM322

MPPS™ Miniature Package Power Solutions 50V NPN LOW SATURATION TRANSISTOR

SUMMARY

$V_{CE0} = 50V$; $R_{SAT} = 68m\Omega$; $I_C = 4A$

DESCRIPTION

Packaged in the innovative 2mm x 2mm MLP (Micro Leaded Package) outline, this new 4th generation low saturation transistor offers extremely low on state losses making it ideal for use in DC-DC circuits and various driving and power management functions.

Additionally users will also gain several other **key benefits**:

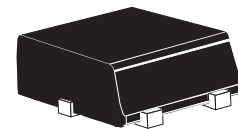
Performance capability equivalent to much larger packages

Improved circuit efficiency & power levels

Lower package height (nom 0.9mm)

PCB area and device placement savings

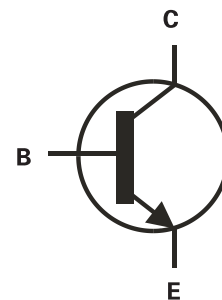
Reduced component count



2mm x 2mm MLP
(single die)

FEATURES

- Low Equivalent On Resistance
- Extremely Low Saturation Voltage (**100mV max @1A**)
- h_{FE} specified up to 6A
- $I_C = 4A$ Continuous Collector Current
- 2mm x 2mm MLP



APPLICATIONS

- DC - DC Converters
- Charging Circuits
- Power switches
- Motor control

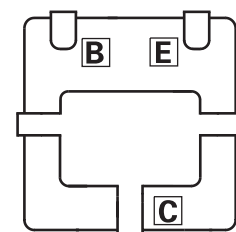
ORDERING INFORMATION

DEVICE	REEL	TAPE WIDTH	QUANTITY PER REEL
ZXTCM322TA	7''	8mm	3000
ZXTCM322TC	13''	8mm	10000

DEVICE MARKING

SC

PINOUT



2mm x 2mm Single MLP
underside view

ZXTCM322

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	50	V
Emitter-Base Voltage	V_{EBO}	7.5	V
Peak Pulse Current (c)	I_{CM}	6	A
Continuous Collector Current (a)	I_C	4	A
Base Current	I_B	1000	mA
Power Dissipation at $T_A=25^{\circ}\text{C}$ (a)	P_D	1.5	W
Linear Derating Factor		12	mW/ $^{\circ}\text{C}$
Power Dissipation at $T_A=25^{\circ}\text{C}$ (b)	P_D	2.45	W
Linear Derating Factor		19.6	mW/ $^{\circ}\text{C}$
Power Dissipation at $T_A=25^{\circ}\text{C}$ (d)	P_D	1	W
Linear Derating Factor		8	mW/ $^{\circ}\text{C}$
Power Dissipation at $T_A=25^{\circ}\text{C}$ (e)	P_D	3	W
Linear Derating Factor		24	mW/ $^{\circ}\text{C}$
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	$^{\circ}\text{C}$

THERMAL RESISTANCE

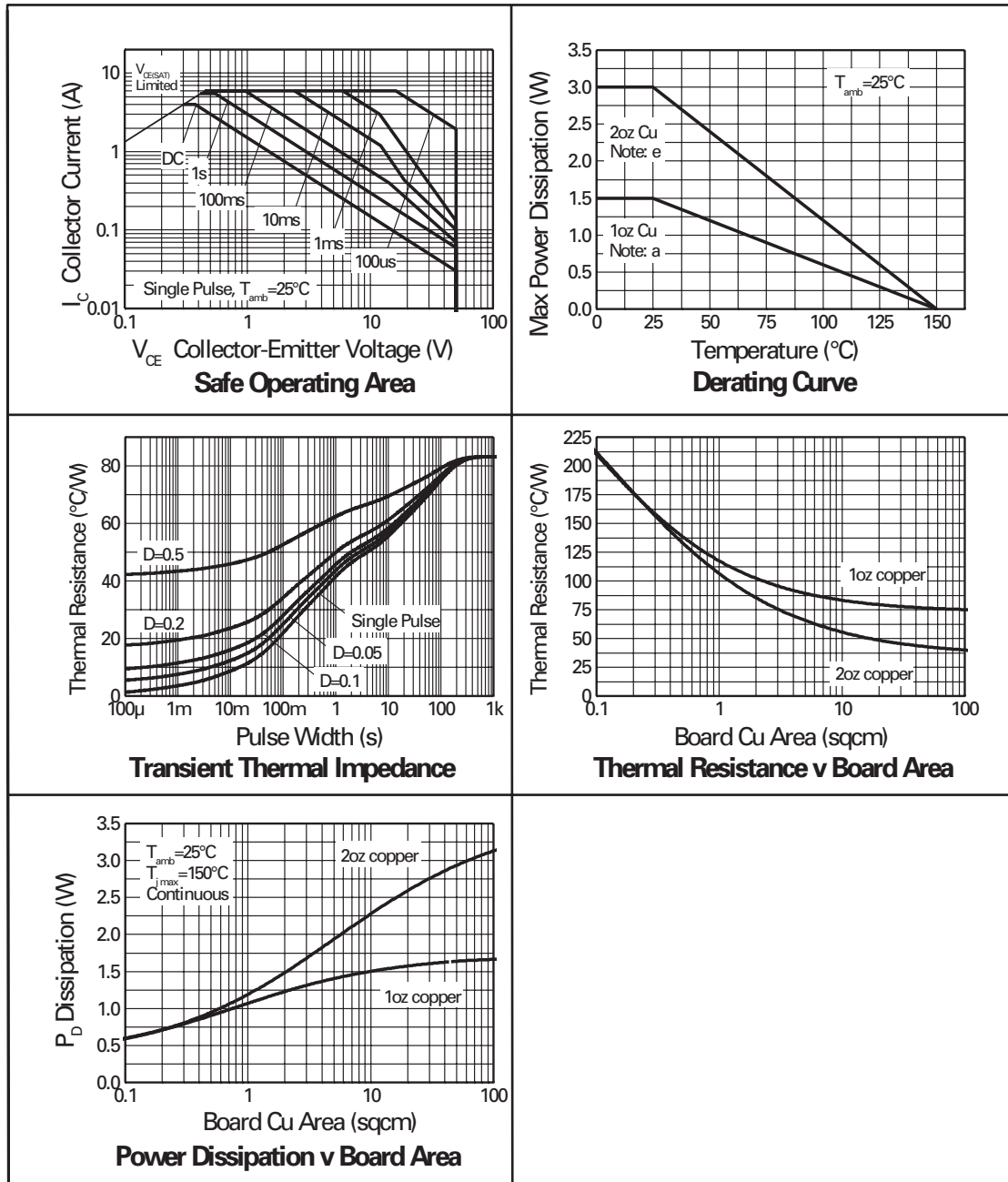
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	83	$^{\circ}\text{C/W}$
Junction to Ambient (b)	$R_{\theta JA}$	51	$^{\circ}\text{C/W}$
Junction to Ambient (d)	$R_{\theta JA}$	125	$^{\circ}\text{C/W}$
Junction to Ambient (e)	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$

NOTES

- (a) For a single device surface mounted on 10sq cm1oz copper on FR4 PCB in still air conditions **with all exposed pads attached**.
- (b) For a single device surface mounted on 10sq cm1oz copper on FR4 PCB in still air conditions measured at $t \leq 5$ secs **with all exposed pads attached**.
- (c) Repetitive rating - pulse width limited by max junction temperature. refer to Transient Thermal Impedance graph.
- (d) For a single device surface mounted on 10sq cm1oz copper on FR4 PCB in still air conditions **with minimal lead connections only**.
- (e) For a single device surface mounted on 65sq cm2oz copper on FR4 PCB in still air conditions **with all exposed pads attached**.
- (f) The minimum copper dimensions requires for mounting are no smaller than the exposed metal pads on the base of the device, as shown in the package dimensions data. The thermal resistance for a device mounted on 1.5mm thick FR4 board using minimum copper of 1oz weight and 1mm wide wide tracks is $R_{th}=300^{\circ}\text{C}$ giving a power rating of $P_{tot}=420\text{mW}$.

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TYPICAL CHARACTERISTICS



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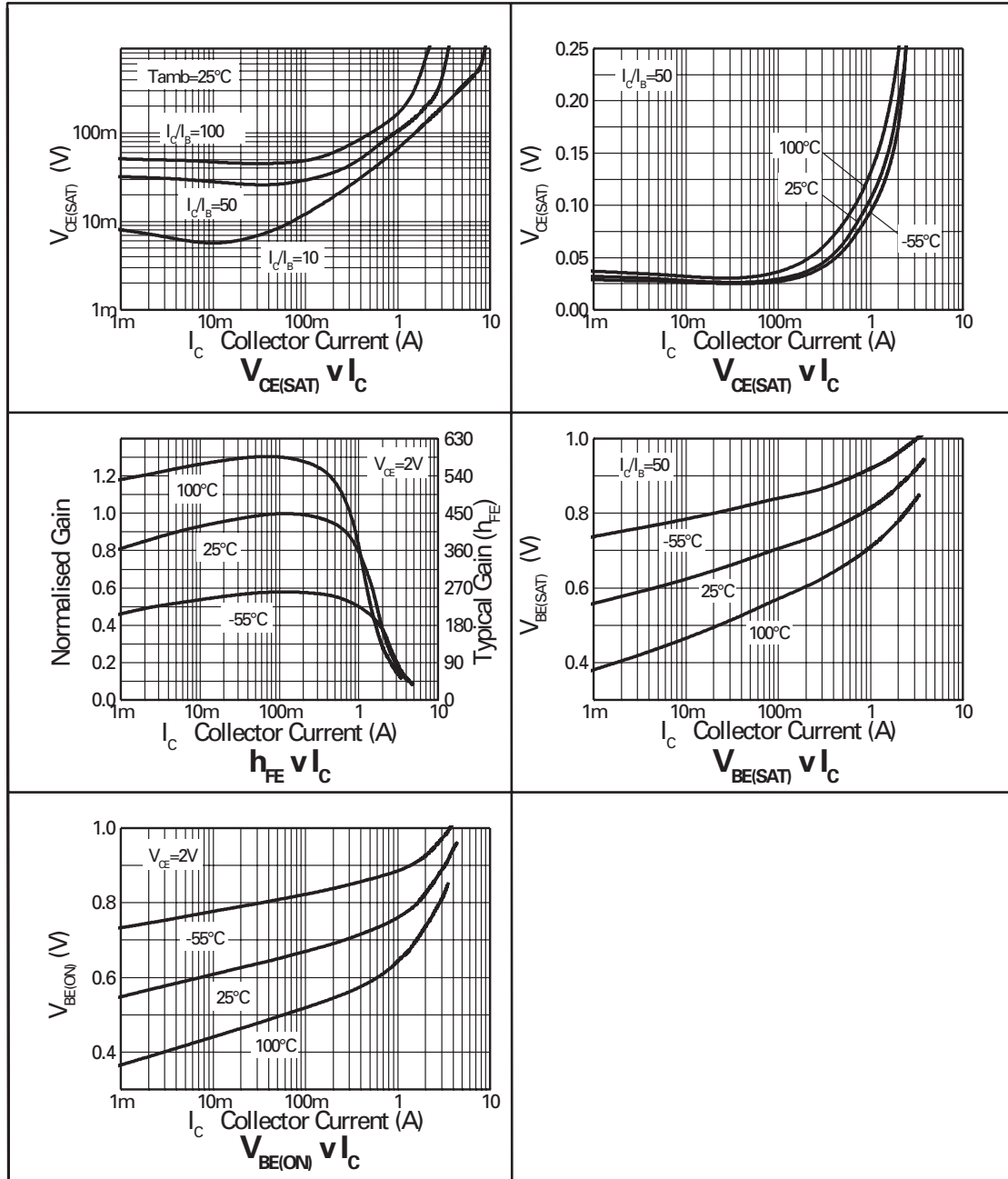
ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	100	190		V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	50	65		V	$I_C = 10\text{mA}^*$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	7.5	8.2		V	$I_E = 100\mu\text{A}$
Collector Cut-Off Current	I_{CBO}			25	nA	$V_{CB} = 80\text{V}$
Emitter Cut-Off Current	I_{EBO}			25	nA	$V_{EB} = 6\text{V}$
Collector Emitter Cut-Off Current	I_{CES}			25	nA	$V_{CES} = 40\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$		10 70 145 115 225 270	20 100 200 220 300 320	mV mV mV mV mV mV	$I_C = 0.1\text{A}, I_B = 10\text{mA}^*$ $I_C = 1\text{A}, I_B = 50\text{mA}^*$ $I_C = 1\text{A}, I_B = 10\text{mA}^*$ $I_C = 2\text{A}, I_B = 50\text{mA}^*$ $I_C = 3\text{A}, I_B = 100\text{mA}^*$ $I_C = 4\text{A}, I_B = 200\text{mA}^*$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$		1.00	1.05	V	$I_C = 4\text{A}, I_B = 200\text{mA}^*$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$		0.94	1.00	V	$I_C = 4\text{A}, V_{CE} = 2\text{V}^*$
Static Forward Current Transfer Ratio	h_{FE}	200 300 200 100	400 450 400 225 40			$I_C = 10\text{mA}, V_{CE} = 2\text{V}^*$ $I_C = 0.2\text{A}, V_{CE} = 2\text{V}^*$ $I_C = 1\text{A}, V_{CE} = 2\text{V}^*$ $I_C = 2\text{A}, V_{CE} = 2\text{V}^*$ $I_C = 6\text{A}, V_{CE} = 2\text{V}^*$
Transition Frequency	f_T	100	165		MHz	$I_C = 50\text{mA}, V_{CE} = 10\text{V}$ $f = 100\text{MHz}$
Output Capacitance	C_{obo}		12	20	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Turn-On Time	$t_{(on)}$		170		ns	$V_{CC} = 10\text{V}, I_C = 1\text{A}$ $I_{B1} = I_{B2} = 10\text{mA}$
Turn-Off Time	$t_{(off)}$		750		ns	

*Measured under pulsed conditions. Pulse width=300 μs . Duty cycle $\leq 2\%$

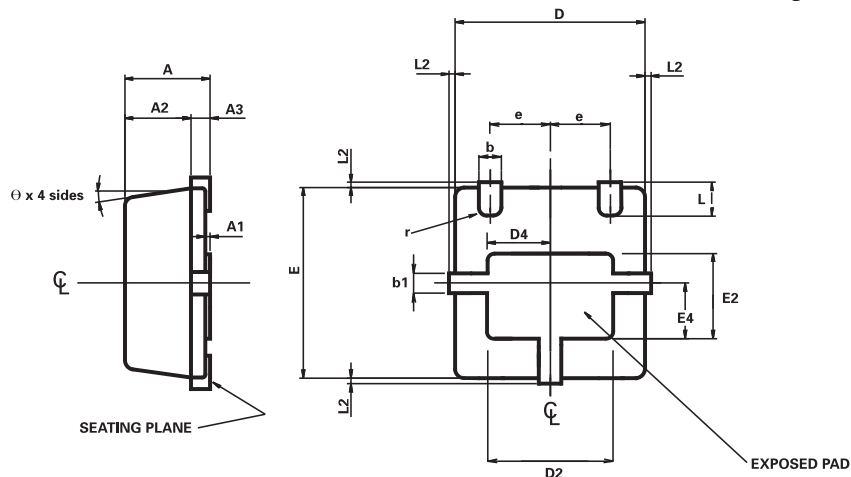
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TYPICAL CHARACTERISTICS



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MLP322 PACKAGE OUTLINE (2mm x 2mm Micro Leaded Package)



CONTROLLING DIMENSIONS IN MILLIMETRES
APPROX. CONVERTED DIMENSIONS IN INCHES

PACKAGE DIMENSIONS

DIM	MILLIMETRES		INCHES		DIM	MILLIMETRES		INCHES	
	MIN.	MAX.	MIN.	MAX.		MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.0315	0.0393	e	0.65 REF		0.0255 REF	
A1	0.00	0.05	0.00	0.002	E	2.00 BSC		0.0787 BSC	
A2	0.65	0.75	0.0255	0.0295	E2	0.79	0.99	0.031	0.039
A3	0.15	0.25	0.0059	0.0098	E4	0.48	0.68	0.0188	0.0267
b	0.18	0.28	0.0070	0.0110	L	0.20	0.45	0.0078	0.0177
b1	0.17	0.30	0.0066	0.0118	L2	0.125 MAX.		0.005 REF	
D	2.00 BSC		0.0787 BSC		r	0.075 BSC		0.0029 BSC	
D2	1.22	1.42	0.0480	0.0559	Θ	0°	12°	0°	12°
D4	0.56	0.76	0.0220	0.0299					

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